

MATERIAL DECLARATION SHEET



Material Number	CM453232 series(1R0-101)			
Product Line	Wound Chip Inductor			
Compliance Date	2022/9/2			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	Ferrite	0.03	Iron oxide (Fe2O3)	1309-37-1	63.0	17.18	27.27
				Nickel oxide (NiO)	1313-99-1	12.0	3.27	
				Zinc oxide (ZnO)	1314-13-2	18.0	4.91	
				Copper oxide(CuO)	1317-38-0	7.0	1.91	
2	Winding Wire	Copper	0.016	Copper(Cu)	7440-50-8	95.0	13.81	14.54
				Polyesterimide	confidential	5.0	0.73	
3	Terminal	Copper	0.035	Copper (Cu)	7440-50-8	95.0	30.23	31.82
				Tin (Sn)	7440-31-5	5.0	1.59	
4	Adhesive	Resin	0.015	BISPHENOL A DIGLYCIDYL ETHER RESIN	25068-38-6	65.0	8.86	13.64
				Dicyanodiamide	461-58-5	6.0	0.82	
				Titanium dioxide	13463-67-7	4.0	0.55	
				Silicon dioxide	7631-86-9	25.0	3.41	

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5	Molding Compound	Silica	0.01	silica	60676-86-0	69.0	6.27	9.09
				Antimony(III) oxide	1309-64-4	2.5	0.23	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0	1.36	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	0.91	
				Brominated epoxy resin	40039-93-8	2.5	0.23	
				Carbon black	1333-86-4	1.0	0.09	
6	Solder	Tin	0.004	Tin (Sn)	7440-31-5	100	3.64	3.64
		Total weight	0.11					

This Document was updated on: 2022/9/2

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.